

C5799

Conductor

Description

C5799 is a screen printable gold via fill conductor designed for use in multilayer hybrids. It is designed to be used with either IP9117 or IP9118. It gives excellent surface coplanarity along with good electrical conductivity.

Key Features

- Outstanding via fill to dielectric adhesion Excellent surface coplanarity Good conductivity Easy to process Ideal interface for Au bearing conductors



This picture does not show the packaging of C5799 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Conductivity	≤ 15.0 milliohms/square at 25 μm fired film thickness
Viscosity	250 – 400 Kcps Brookfield HBT SC4 – 14 spindle and 6R utility cup at 10 rpm, 25 °C
Solids	86.0 ± 1.0 %
Coverage	68 cm ² /g at 25 μm fired film thickness
Metal	Au

Recommended Processing Guide

Printing Parameters	325 mesh stainless steel screen 0.8 mil emulsion
Drying Temperature	150 °C for 10 minutes
Process Temperature (TDS)	875 °C peak temperature Dwell time of 8 – 12 minutes
Film Thickness	20 – 26 μm
Recommended Thinner	RV-372
Paste Compatibility	Conductors C 5789, C 5790 Dielectric IP 9118, IP 9117W, IP 9117

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Warranty

6 months

Storage

Store in a dry location at 5°C-25°C

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